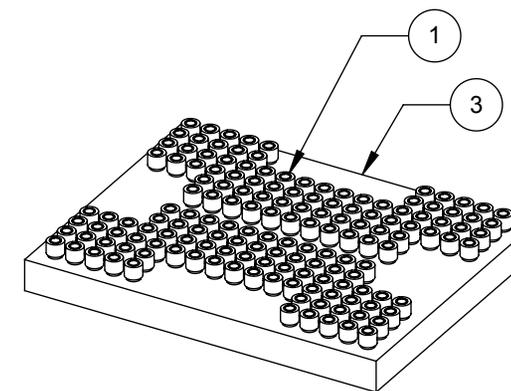
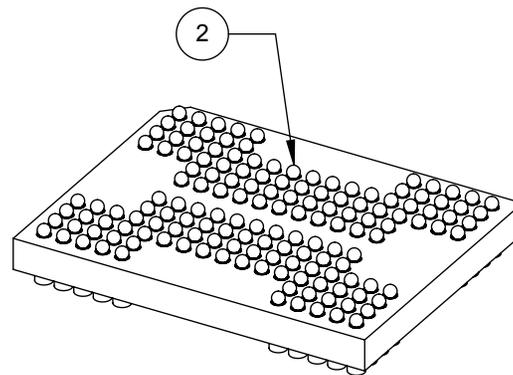
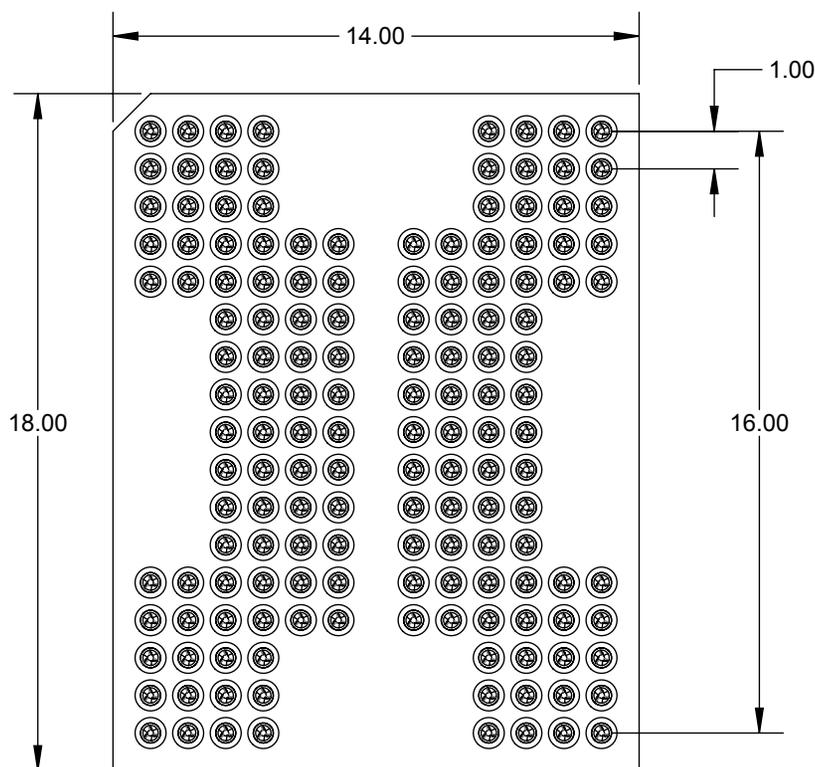
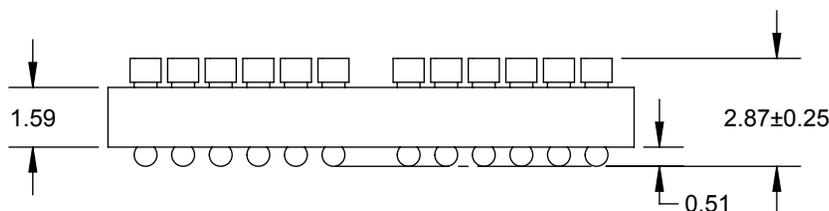


U.S. Patent No. 8,091,222 B2



ITEM NO.	DESCRIPTION	Material
1	P-S519A, Socket Pin, 1.0mm centers minimum, #4 clip	Body - Gold Plated Brass 360, Clip - Gold plated Beryllium Copper 172
2	Solder Ball, 0.024" Dia	see table
3	Non-clad substrate	FR4 Standard



Description: SF-BGA152C-B-42F 14mm x 18mm, 13x17 array, 1mm pitch

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.
 Tolerances: Hole diameters $\pm 0.03\text{mm}$ [± 0.001 "], Pitches (from true position) $\pm 0.025\text{mm}$ [± 0.001 "], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

PART NO. SUFFIX	SOLDER BALL ALLOY
-42	Sn63Pb37
-42F*	Sn96.5Ag3.0Cu0.5
*RoHS Compliant	

SF-BGA152C-B-42F Drawing SF-BGA152C-B-42 Drawing		Material: N/A Finish: N/A Weight: 1.03	STATUS: ECO ENG: S. Faiz FILE: SF-BGA152C-B-42 Dwg	SHEET: 1 OF 1 DRAWN BY: M. Raske DATE: 11/20/2014	REV. A SCALE: 5:1
 Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com					